

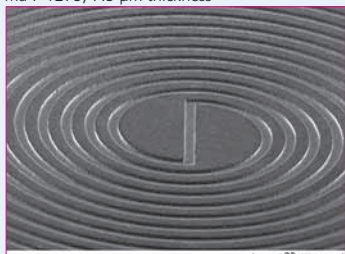
# ma-P 1275 — Positive Tone Photoresist

## Ultra Thick Resist for UV Lithography

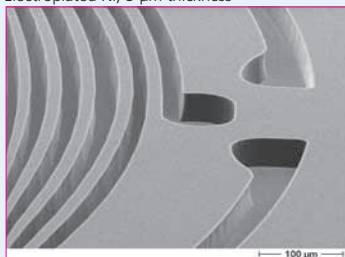
Resist patterning with mask aligner, broadband exposure



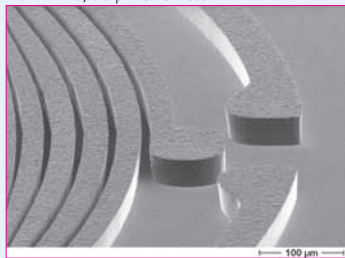
ma-P 1275, 7.5 µm thickness



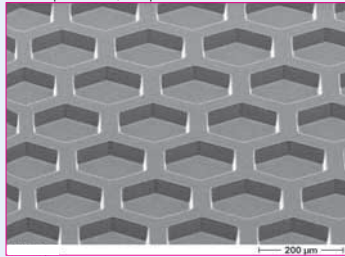
Electroplated Ni, 5 µm thickness



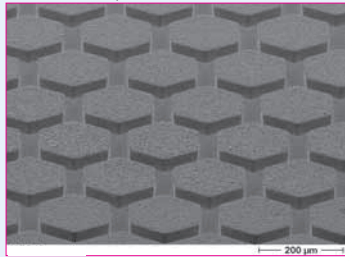
ma-P 1275, 30 µm thickness



Electroplated Ni, 28 µm thickness



ma-P 1275, 40 µm thickness



Electroplated Ni, 38 µm thickness

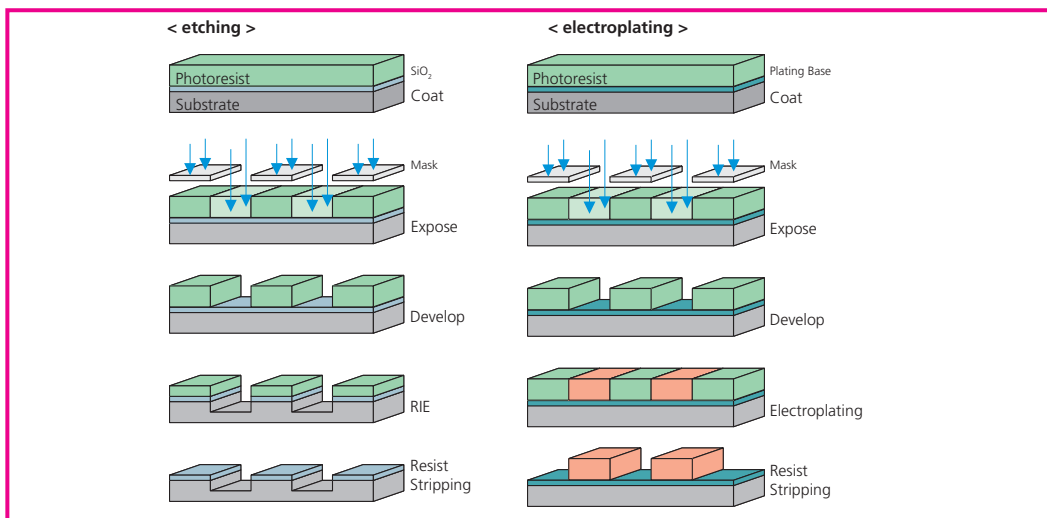
### Unique features

- Outstanding pattern stability in wet etch processes and acid and alkaline plating baths from pH 1 - 13.5
- Highly stable in dry etch processes e.g.  $\text{CHF}_3$ ,  $\text{CF}_4$ ,  $\text{SF}_6$
- Aqueous alkaline development
- Easy to remove
- Side wall angle up to 84°

### Applications

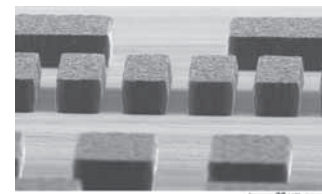
- Moulds for electroplating, e.g.
  - Micro optical components
  - Micro springs
  - Bumping
- Mask for etching e.g.
  - Si,  $\text{SiO}_2$
  - Metals
  - Semiconductors
- Mask for ion implantation

### Process flow



### Technical data

Film thickness	µm	7.5	20	30	40
Spin coating	rpm	3000	500	350	250
Spin time	s	30	90	90	90
Aspect ratio		3 - 4	3 - 4	3 - 4	3 - 4



Cuboid Ni structures, 17 µm thickness

